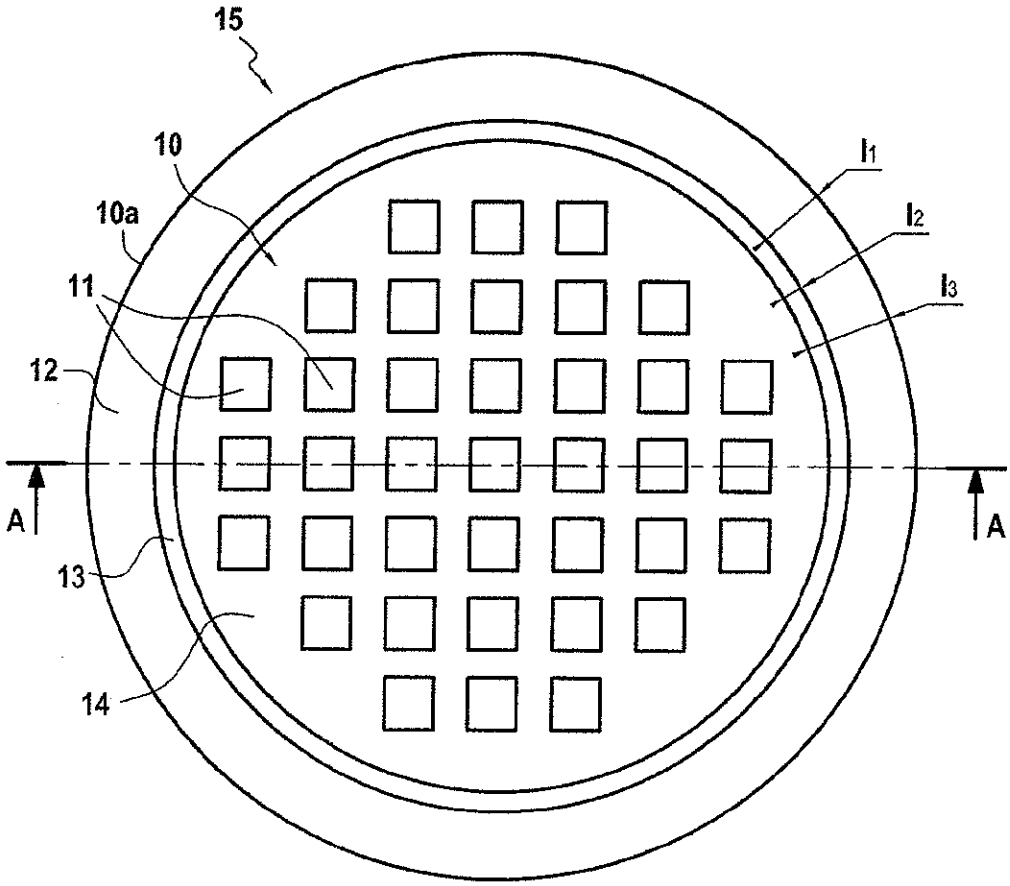


FIG.1

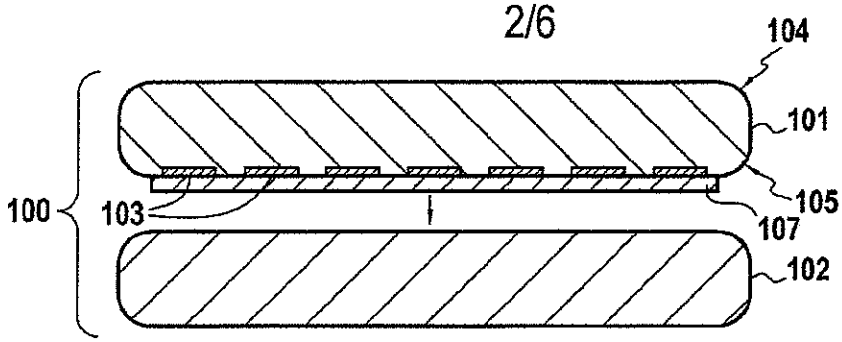


FIG.2A

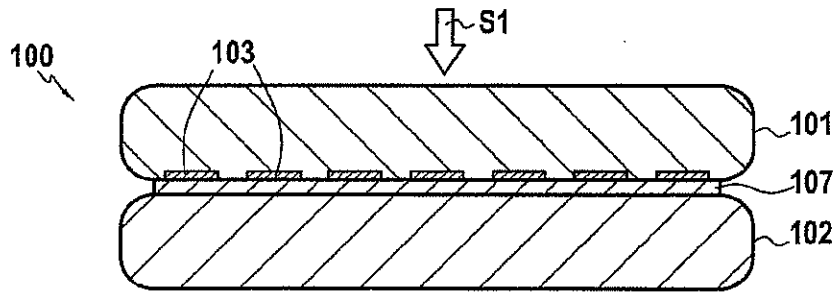


FIG.2B

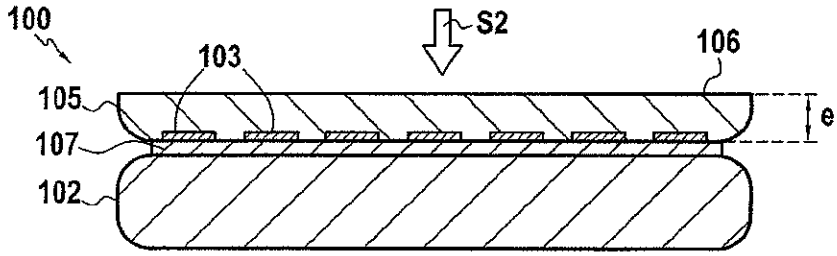


FIG.2C

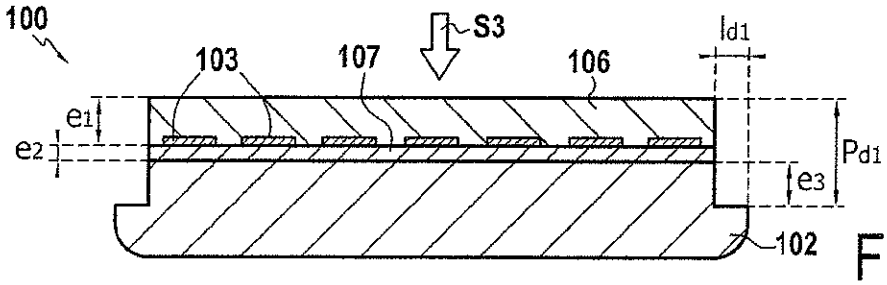


FIG.2D

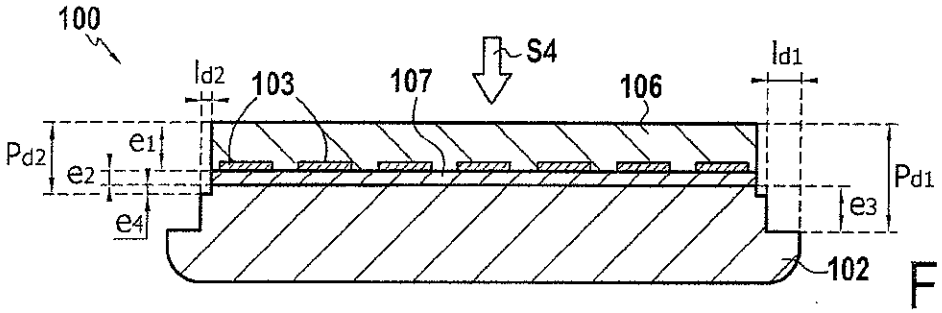


FIG.2E

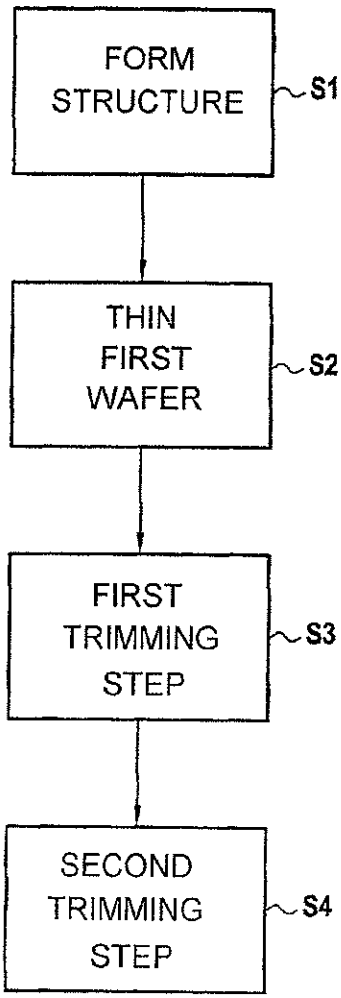

FORM STRUCTURE
S1
THIN FIRST WAFER
S2
FIRST TRIMMING STEP
S3
SECOND TRIMMING STEP
S4

FIG.3

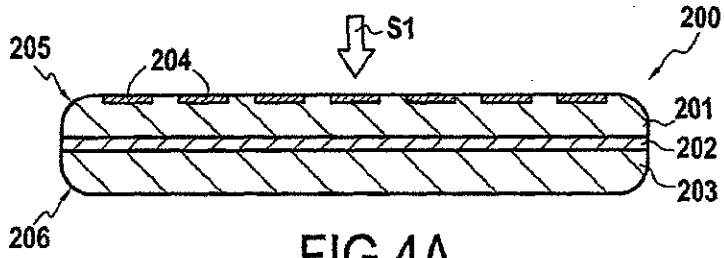


FIG.4A

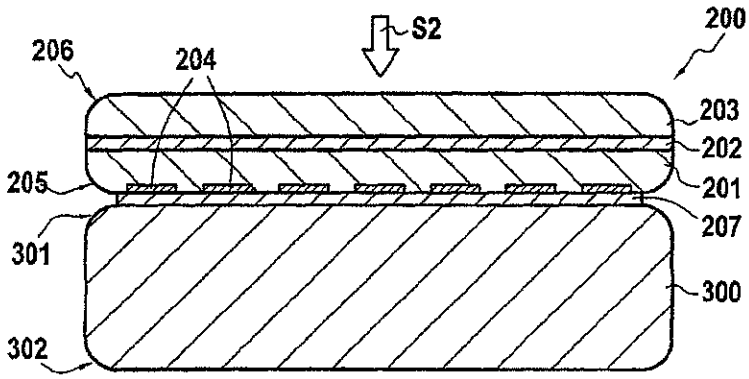


FIG.4B

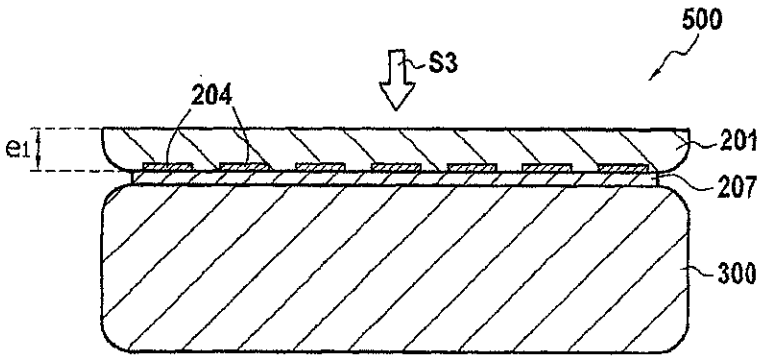


FIG.4C

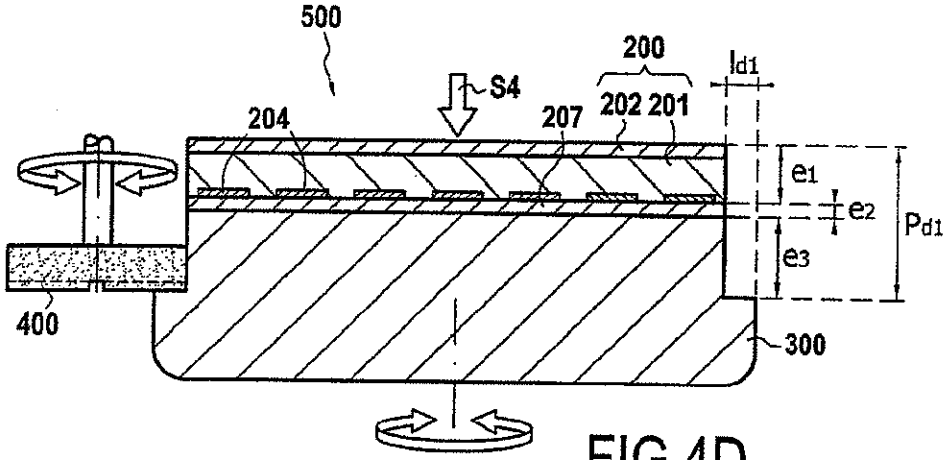


FIG.4D

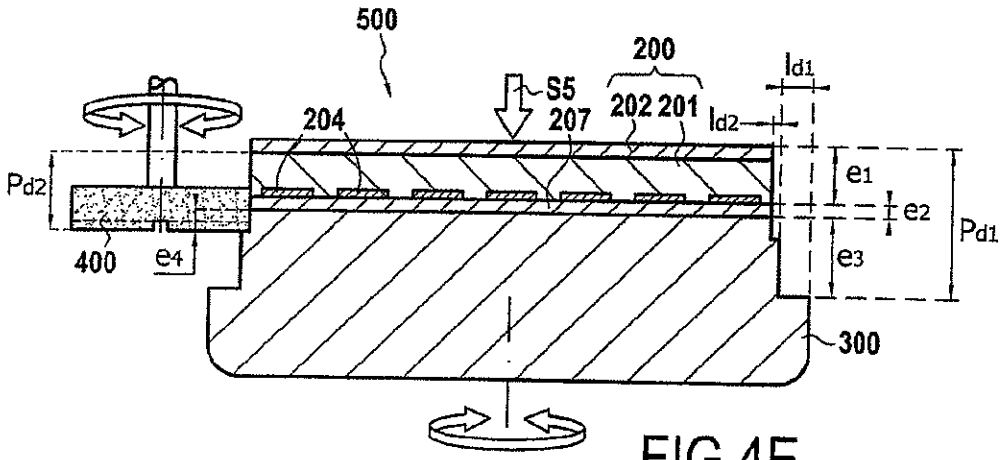


FIG.4E

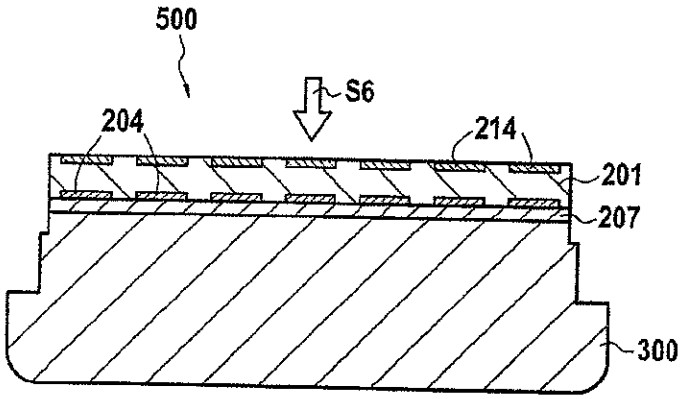


FIG.4F

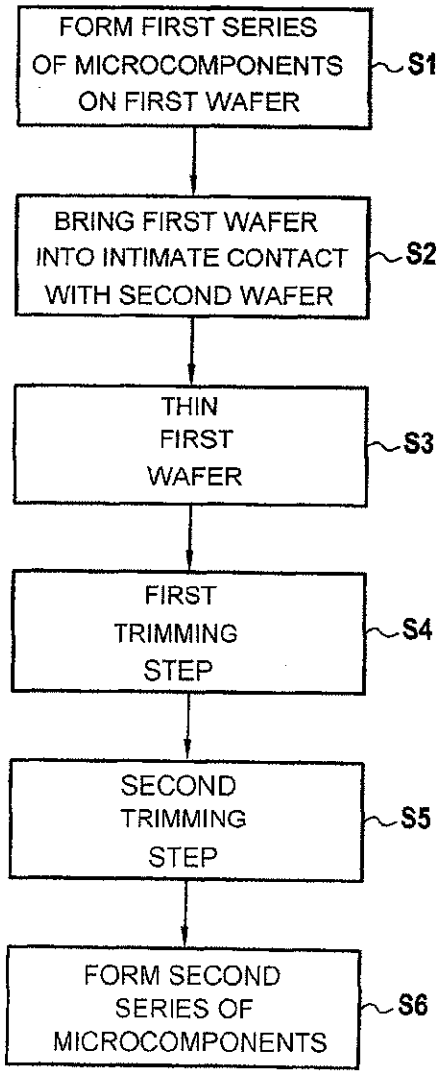

FORM FIRST SERIES OF MICROCOMPONENTS ON FIRST WAFER
S1
BRING FIRST WAFER INTO INTIMATE CONTACT WITH SECOND WAFER
S2
THIN FIRST WAFER
S3
FIRST TRIMMING STEP
S4
SECOND TRIMMING STEP
S5
FORM SECOND SERIES OF MICROCOMPONENTS
S6

FIG.5

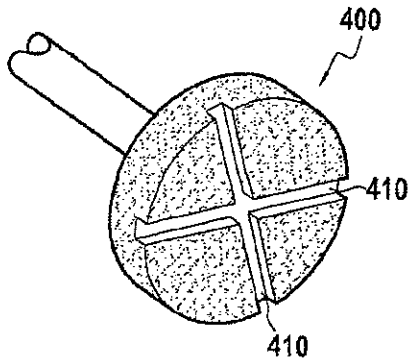

400
410
410

FIG.6